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Renesas Electronics website: http://www.renesas.com

April 1st, 2010 Renesas Electronics Corporation

Issued by: Renesas Electronics Corporation (http://www.renesas.com)

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DATA SHEET

GaAs INTEGRATED CIRCUIT

L, S-BAND SPDT SWITCH

DESCRIPTION

The μ PG2008TK is a GaAs MMIC for L, S-band SPDT (Single Pole Double Throw) switch which were developed for mobile phone and another L, S-band application.

This device can operate frequency from 0.5 to 2.5 GHz, having the low insertion loss and high isolation.

This device is housed in a 6-pin lead-less minimold package (1511). And this package is able to high-density surface mounting.

FEATURES

•	Switch control voltage	: V _{cont (H)} = 2.5 to 5.3 V (2.8 V TYP.)
		: $V_{\text{cont (L)}} = -0.2 \text{ to } +0.2 \text{ V} (0 \text{ V TYP.})$
٠	Low insertion loss	: LINS1 = 0.40 dB TYP. @ f = 0.5 to 1.0 GHz, V_{cont} = 2.8 V/0 V
		: Lins2 = 0.55 dB TYP. @ f = 2.0 GHz, V _{cont} = 2.8 V/0 V
		: Lins3 = 0.60 dB TYP. @ f = 2.5 GHz, V _{cont} = 2.8 V/0 V
٠	High isolation	: ISL1 = 25 dB TYP. @ f = 0.5 to 2.0 GHz, V _{cont} = 2.8 V/0 V
		: ISL2 = 25 dB TYP. @ f = 2.5 GHz, V_{cont} = 2.8 V/0 V
٠	High-density surface mounting	: 6-pin lead-less minimold package (1.5 $ imes$ 1.1 $ imes$ 0.55 mm)

APPLICATIONS

- L-band digital cellular or cordless telephone
- PCS, W-LAN, WLL and Bluetooth[™] etc.

ORDERING INFORMATION

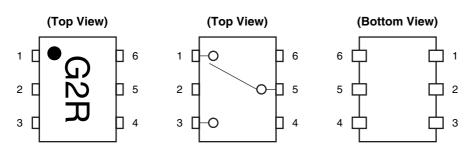
Part Number	Package	Marking	Supplying Form
μPG2008TK-E2	6-pin lead-less minimold (1511)	G2R	 Embossed tape 8 mm wide Pin 1, 6 face the perforation side of the tape Qty 5 kpcs/reel

Remark To order evaluation samples, contact your nearby sales office. Part number for sample order: μ PG2008TK

Caution Observe precautions when handling because these devices are sensitive to electrostatic discharge.

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***** PIN CONNECTIONS AND INTERNAL BLOCK DIAGRAM



-	
Pin No.	Pin Name
1	OUTPUT1
2	GND
3	OUTPUT2
4	V _{cont2}
5	INPUT
6	V _{cont1}

TRUTH TABLE

Vcont1	Vcont2	INPUT-OUTPUT1	INPUT-OUTPUT2
Low	High	ON	OFF
High	Low	OFF	ON

ABSOLUTE MAXIMUM RATINGS (TA = +25°C, unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Switch Control Voltage	Vcont	-6.0 to +6.0 ^{Note 1}	V
Input Power	Pin	+28	dBm
Power Dissipation	PD	150 ^{Note 2}	mW
Operating Ambient Temperature	TA	–45 to +85	°C
Storage Temperature	Tstg	–55 to +150	°C

Notes 1. $|V_{cont1}-V_{cont2}| \le 6.0 V$

2. Mounted on double-sided copper-clad $50 \times 50 \times 1.6$ mm epoxy glass PWB, T_A = +85°C

RECOMMENDED OPERATING RANGE (TA = +25°C, unless otherwise specified)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Switch Control Voltage (H)	Vcont (H)	2.5	2.8	5.3	V
Switch Control Voltage (L)	Vcont (L)	-0.2	0	0.2	V

ELECTRICAL CHARACTERISTICS

(TA = +25°C, V_{cont} = 2.8 V/0 V, DC cut capacitors = 56 pF, unless otherwise specified)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Insertion Loss1	LINS1	f = 0.5 to 1.0 GHz	_	0.40	0.70	dB
Insertion Loss2	LINS2	f = 2.0 GHz	_	0.55	0.80	dB
Insertion Loss3	LINS3	f = 2.5 GHz	_	0.60	0.85	dB
Isolation1	ISL1	f = 0.5 to 2.0 GHz	22	25	_	dB
Isolation2	ISL2	f = 2.5 GHz	20	25	-	dB
Input Return Loss	RLin	f = 0.5 to 2.5 GHz	13	20	_	dB
Output Return Loss	RLout	f = 0.5 to 2.5 GHz	13	20	_	dB
1 dB Gain Compression Input Power Note	Pin (1 dB)	f = 2.0 GHz	+20.0	+25.0	-	dBm
Switching Control Current	Icont		_	0.5	10	μA

Note Pin (1 dB) is measured the input power level when the insertion loss increases more 1 dB than that of linear range.

STANDARD CHARACTERISTICS FOR REFERENCE

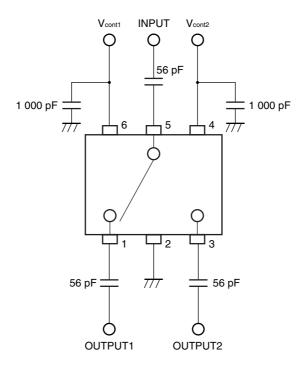
(TA = +25°C, V_{cont} = 2.8 V/0 V, DC cut capacitors = 56 pF, unless otherwise specified)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
0.1 dB Gain Compression Input Power ^{Note}	Pin (0.1 dB)	f = 2.0 GHz	_	+20.0	-	dBm
Switching Control Speed	tsw		-	50	-	ns

Note P_{in (0.1 dB)} is measured the input power level when the insertion loss increases more 0.1 dB than that of linear range.

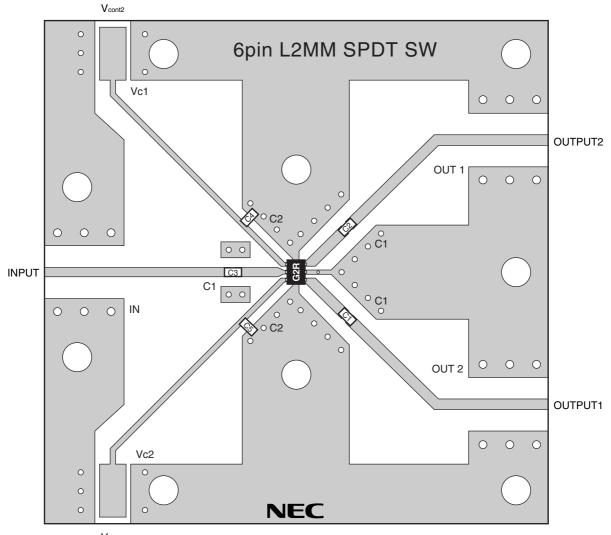
Caution This device is used it is necessary to use DC cut capacitors. The value of DC cut capacitors should be chosen to accommodate the frequency of operation, bandwidth, switching speed and the condition with actual board of your system. The range of recommended DC cut capacitor value is less than 100 pF.

EVALUATION CIRCUIT (V_{cont} = 2.8 V/0 V, DC cut capacitors = 56 pF)



The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

ILLUSTRATION OF THE TEST CIRCUIT ASSEMBLED ON EVALUATION BOARD



Vcont1

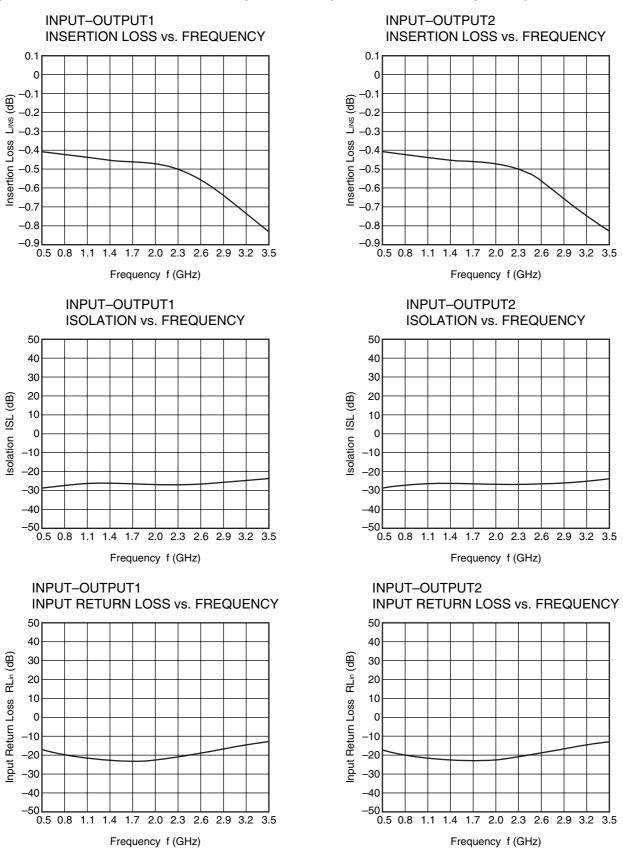
USING THE NEC EVALUATION BOARD

Symbol	Values
C1, C2, C3	56 pF
C4, C5	1 000 pF

Phase-out/Discontinued

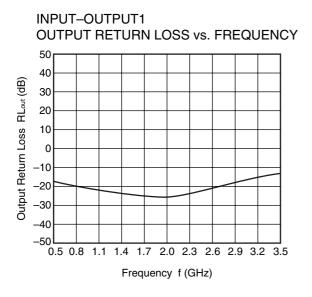
TYPICAL CHARACTERISTICS

(TA = +25°C, V_{cont} = 2.8 V/0 V, DC cut capacitors = 56 pF, unless otherwise specified)

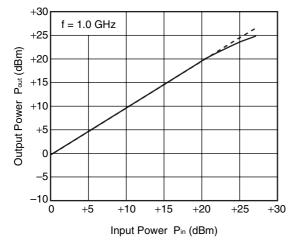




Data Sheet PG10217EJ03V0DS

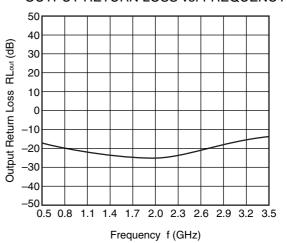


OUTPUT POWER vs. INPUT POWER

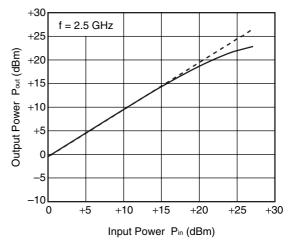


Remark The graphs indicate nominal characteristics.

INPUT-OUTPUT2 OUTPUT RETURN LOSS vs. FREQUENCY

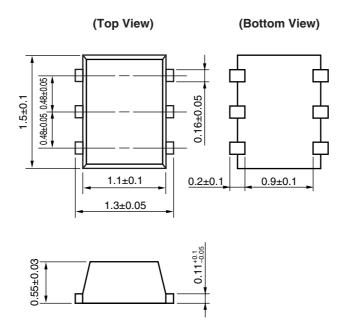


OUTPUT POWER vs. INPUT POWER



★ PACKAGE DIMENSIONS

6-PIN LEAD-LESS MINIMOLD (1511) (UNIT: mm)



RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions		Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature) Time at peak temperature Time at temperature of 220°C or higher Preheating time at 120 to 180°C Maximum number of reflow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 60 seconds or less : 120±30 seconds : 3 times : 0.2%(Wt.) or below	IR260
VPS	Peak temperature (package surface temperature) Time at temperature of 200°C or higher Preheating time at 120 to 150°C Maximum number of reflow processes Maximum chlorine content of rosin flux (% mass)	: 215°C or below : 25 to 40 seconds : 30 to 60 seconds : 3 times : 0.2%(Wt.) or below	VP215
Wave Soldering	Peak temperature (molten solder temperature) Time at peak temperature Preheating temperature (package surface temperature) Maximum number of flow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 120°C or below : 1 time : 0.2%(Wt.) or below	WS260
Partial Heating	Peak temperature (pin temperature) Soldering time (per side of device) Maximum chlorine content of rosin flux (% mass)	: 350°C or below : 3 seconds or less : 0.2%(Wt.) or below	HS350

Caution Do not use different soldering methods together (except for partial heating).

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M8E 00.4-0110

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	Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
	• Do not burn, destroy, cut, crush, or chemically dissolve the product.
	• Do not lick the product or in any way allow it to enter the mouth.

 \blacktriangleright For further information, please contact

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